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(54) **SEMICONDUCTOR DEVICE PACKAGE**

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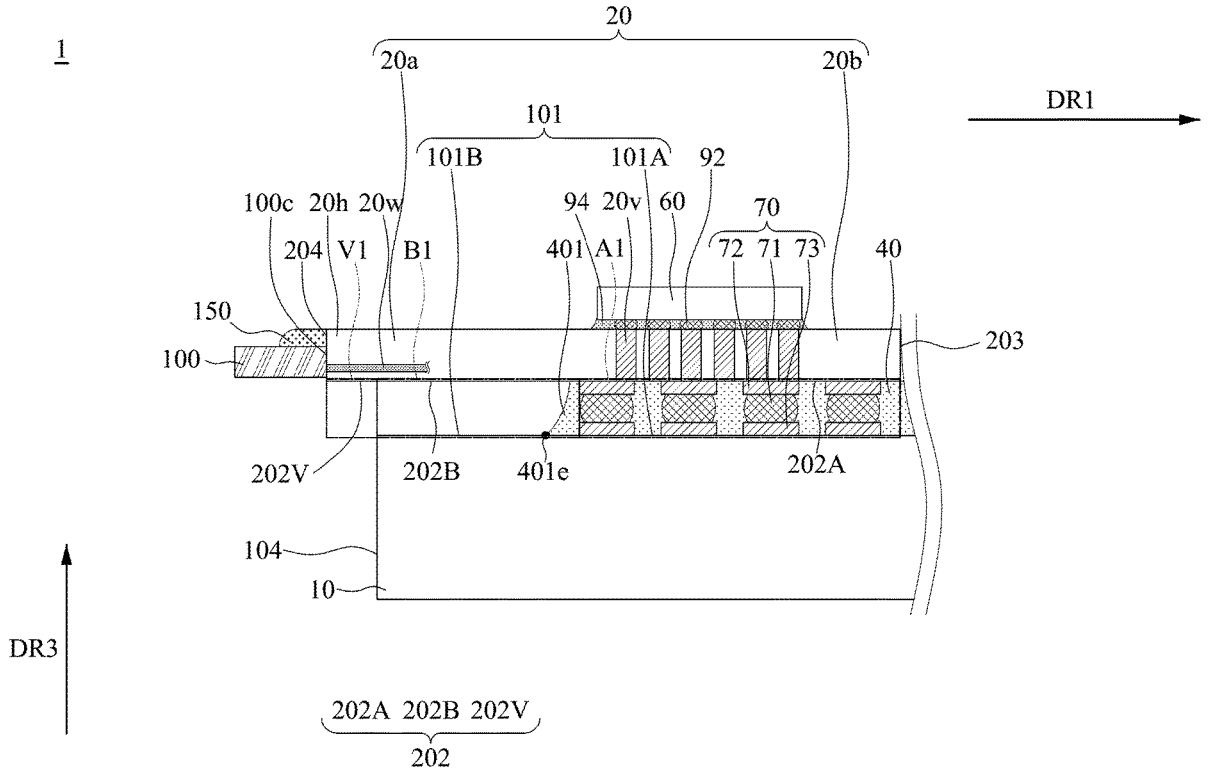
(57) **ABSTRACT**

A package is provided. The package includes a carrier, a component, and a first protective element. The component is disposed over the carrier and having a side surface configured for optically coupling. The first protective element is disposed between the carrier and the component. The side surface of the component is free from being in contact with the first protective element.